

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Previously presented): Electronic component having a plastic housing that includes at least one metallic soldering area, characterized in that the surface of the plastic housing, except for the metallic soldering area, is at least partially covered by an anti-solder coating.
2. (Currently amended): Electronic component as in Claim 1 or 28 or 29 or 30 or 31, characterized in that the anti-solder coating essentially consists of siloxane.
3. (Previously presented): Electronic component as in Claim 1, characterized in that the anti-solder coating essentially consists of polysiloxane.
4. (Currently amended): Electronic component as in Claim 1 or 28 or 29 or 30 or 31, characterized in that the anti-solder coating is essentially based on methyl-polysiloxane.
5. (Currently amended): Electronic component as in Claim 1 or 28 or 29 or 30 or 31, characterized in that the anti-solder coating is essentially based on dimethyl-polysiloxane.
6. (Currently amended): Electronic component as in Claim 1 or 28 or 29 or 30 or 31, characterized in that the anti-solder coating is essentially based on polyether-modified dimethyl-polysiloxane.
7. (Previously presented): Electronic component as in claim 1, characterized in that the plastic housing contains a radiation-emitting and/or radiation-detecting semi-conductor element that is embedded in transparent plastic for the emitted and/or received radiation.

Claims 8-26 (Cancelled)

27. (Previously presented): Electronic component as in claim 1 wherein said component is a surface-mountable radiation-emitting and/or radiation-sensitive electro-optical component.

28. (Currently amended): Electronic component having a plastic housing that includes at least one metallic soldering area, characterized in that the surface of the plastic housing, except for the metallic soldering area, is at least partially covered by an anti-solder coating, electronic component as in claim 1 wherein said component is an unsoldered component.
29. (New): Electronic component having a plastic housing that includes at least one metallic soldering area, characterized in that the surface of the plastic housing, except for the metallic soldering area, is at least partially covered by an anti-solder coating prior to soldering of said component at said soldering area.
30. (New) Electronic component having a plastic housing that includes at least one metallic soldering area, characterized in that the surface of the plastic housing, except for the metallic soldering area, is at least partially covered by an anti-solder coating, wherein said component is apart from any support structure.
31. (New) Electronic component having a plastic housing that includes at least one metallic soldering area, characterized in that the surface of the plastic housing, except for the metallic soldering area, is at least partially covered by an anti-solder coating, wherein said coating has an end, and said coating ends at said component.